## Features

- $12 \mathrm{MHz}-3 \mathrm{~dB}$ Bandwidth
- Unity gain buffer
- Supply voltage $=4.5 \mathrm{~V}$ to 16.5 V
- Low supply current (per buffer) = $500 \mu \mathrm{~A}$
- High slew rate $=10 \mathrm{~V} / \mu \mathrm{s}$
- Rail to Rail operation
- "Mini" SO Package (MSOP)


## Applications

- TFT-LCD Drive Circuits
- Electronics Notebooks
- Electronics Games
- Personal Communication Devices
- Personal Digital Assistants (PDA)
- Portable Instrumentation
- Wireless LANs
- Office Automation
- Active Filters
- ADC/DAC Buffer


## Ordering Information

| Part No. | Temp. Range | Package | Outline \# |
| :---: | :---: | :---: | :---: |
| EL5421 CY | $-40^{\circ} \mathrm{C}$ to $+85^{\circ} \mathrm{C}$ | 10 -Pin MSOP | MDP0043 |

## General Description

The EL5421C is a quad, low power, high voltage rail-to-rail input-output buffer. Operating on supplies ranging from 5 V to 15 V , while consuming only $500 \mu \mathrm{~A}$ per channel, the EL5421C has a bandwidth of $12 \mathrm{MHz}(-3 \mathrm{~dB})$. The EL5421C also provides rail-to-rail input and output ability, giving the maximum dynamic range at any supply voltage.

The EL5421C also features fast slewing and settling times, as well as a high output drive capability of 30 mA (sink and source). These features make the EL5421C ideal for use as voltage reference buffers in Thin Film Transistor Liquid Crystal Displays (TFT-LCD). Other applications include battery power, portable devices and anywhere low power consumption is important.
The EL5421C is available in a space saving 10-Pin MSOP package and operates over a temperature range of $-40^{\circ} \mathrm{C}$ to $+85^{\circ} \mathrm{C}$.

## Connection Diagram



## EL5421C

## Quad 12MHz Rail-to-Rail Input-Output Buffer

## Absolute Maximum Ratings $\left(\mathrm{T}_{\mathrm{A}}=25^{\circ} \mathrm{C}\right)$

Values beyond absolute maximum ratings can cause the device to be prematurely damaged. Absolute maximum ratings are stress ratings only and functional device operation is not implied
Supply Voltage between $\mathrm{V}_{\mathrm{S}}+$ and $\mathrm{V}_{\mathrm{S}}-$
$+18 \mathrm{~V}$
Input Voltage
Maximum Continuous Output Current

$$
\mathrm{V}_{\mathrm{S}}--0.5 \mathrm{~V}, \mathrm{~V}_{\mathrm{S}}++0.5 \mathrm{~V}
$$

$$
30 \mathrm{~mA}
$$

Maximum Die Temperature
$+125^{\circ} \mathrm{C}$
Storage Temperature $65^{\circ} \mathrm{C}$ to $+150^{\circ} \mathrm{C}$
Operating Temperature
Power Dissipation
ESD Voltage
See Curves
2 kV

## Important Note:

All parameters having Min/Max specifications are guaranteed. Typ values are for information purposes only. Unless otherwise noted, all tests are at the specified temperature and are pulsed tests, therefore: $\mathbf{T}_{J}=\mathbf{T}_{\mathbf{C}}=\mathbf{T}_{\mathbf{A}}$

## Electrical Characteristics

$\mathrm{V}_{\mathrm{S}_{+}}=+5 \mathrm{~V}, \mathrm{~V}_{\mathrm{S}^{-}}=-5 \mathrm{~V}, \mathrm{R}_{\mathrm{L}}=10 \mathrm{k} \Omega$ and $\mathrm{C}_{\mathrm{L}}=10 \mathrm{pF}$ to $0 \mathrm{~V}, \mathrm{TA}=25^{\circ} \mathrm{C}$ unless otherwise specified.

| Parameter | Description | Condition | Min | Typ | Max | Unit |
| :---: | :---: | :---: | :---: | :---: | :---: | :---: |
| Input Characteristics |  |  |  |  |  |  |
| V ${ }_{\text {OS }}$ | Input Offset Voltage | $\mathrm{V}_{\mathrm{CM}}=0 \mathrm{~V}$ |  | 2 | 12 | mV |
| $\mathrm{TCV}_{\text {OS }}$ | Average Offset Voltage Drift | [1] |  | 5 |  | $\mu \mathrm{V} /{ }^{\circ} \mathrm{C}$ |
| $\mathrm{I}_{\mathrm{B}}$ | Input Bias Current | $\mathrm{V}_{\mathrm{CM}}=0 \mathrm{~V}$ |  | 2 | 50 | nA |
| $\mathrm{R}_{\text {IN }}$ | Input Impedance |  |  | 1 |  | $\mathrm{G} \Omega$ |
| $\mathrm{C}_{\text {IN }}$ | Input Capacitance |  |  | 1.35 |  | pF |
| $\mathrm{A}_{\mathrm{V}}$ | Voltage Gain | $-4.5 \mathrm{~V} \leq \mathrm{V}_{\text {OUT }} \leq 4.5 \mathrm{~V}$ | 0.995 |  | 1.005 | V/V |
| Output Characteristics |  |  |  |  |  |  |
| $\mathrm{V}_{\mathrm{OL}}$ | Output Swing Low | $\mathrm{I}_{\mathrm{L}}=-5 \mathrm{~mA}$ |  | -4.92 | -4.85 | V |
| $\mathrm{V}_{\mathrm{OH}}$ | Output Swing High | $\mathrm{I}_{\mathrm{L}}=5 \mathrm{~mA}$ | 4.85 | 4.92 |  | V |
| $\mathrm{I}_{\text {SC }}$ | Short Circuit Current | Short to GND ${ }^{\text {[2] }}$ | $\pm 80$ | $\pm 120$ |  | mA |
| Power Supply Performance |  |  |  |  |  |  |
| PSRR | Power Supply Rejection Ratio | $\mathrm{V}_{\mathrm{S}}$ is moved from $\pm 2.25 \mathrm{~V}$ to $\pm 7.75 \mathrm{~V}$ | 60 | 80 |  | dB |
| IS | Supply Current (Per Buffer) | No Load |  | 500 | 750 | $\mu \mathrm{A}$ |
| Dynamic Performance |  |  |  |  |  |  |
| SR | Slew Rate ${ }^{[3]}$ | $-4.0 \mathrm{~V} \leq \mathrm{V}_{\text {OUT }} \leq 4.0 \mathrm{~V}, 20 \%$ to $80 \%$ | 7 | 10 |  | V/ $\mu \mathrm{s}$ |
| $\mathrm{t}_{\mathrm{S}}$ | Settling to +0.1\% | $\mathrm{V}_{\mathrm{O}}=2 \mathrm{~V}$ Step |  | 500 |  | ns |
| BW | -3dB Bandwidth | $\mathrm{R}_{\mathrm{L}}=10 \mathrm{k} \Omega, \mathrm{C}_{\mathrm{L}}=10 \mathrm{pF}$ |  | 12 |  | MHz |
| CS | Channel Separation | $\mathrm{f}=5 \mathrm{MHz}$ |  | 75 |  | dB |

1. Measured over the operating temperature range
2. Parameter is guaranteed (but not test) by design and characterization data
3. Slew rate is measured on rising and falling edges

## Electrical Characteristics

$\mathrm{V}_{\mathrm{S}^{+}}=+5 \mathrm{~V}, \mathrm{~V}_{\mathrm{S}^{-}}=0 \mathrm{~V}, \mathrm{R}_{\mathrm{L}}=10 \mathrm{k} \Omega$ and $\mathrm{C}_{\mathrm{L}}=10 \mathrm{pF}$ to $2.5 \mathrm{~V}, \mathrm{TA}=25^{\circ} \mathrm{C}$ unless otherwise specified.

| Parameter | Description | Condition | Min | Typ | Max | Unit |
| :---: | :---: | :---: | :---: | :---: | :---: | :---: |
| Input Characteristics |  |  |  |  |  |  |
| $\mathrm{V}_{\text {OS }}$ | Input Offset Voltage | $\mathrm{V}_{\mathrm{CM}}=2.5 \mathrm{~V}$ |  | 2 | 10 | mV |
| $\mathrm{TCV}_{\text {OS }}$ | Average Offset Voltage Drift | [1] |  | 5 |  | $\mu \mathrm{V} /{ }^{\circ} \mathrm{C}$ |
| $\mathrm{I}_{\mathrm{B}}$ | Input Bias Current | $\mathrm{V}_{\mathrm{CM}}=2.5 \mathrm{~V}$ |  | 2 | 50 | nA |
| $\mathrm{R}_{\text {IN }}$ | Input Impedance |  |  | 1 |  | $\mathrm{G} \Omega$ |
| $\mathrm{C}_{\text {IN }}$ | Input Capacitance |  |  | 1.35 |  | pF |
| Av | Voltage Gain | $0.5 \leq \mathrm{V}_{\text {OUT }} \leq 4.5 \mathrm{~V}$ | 0.995 |  | 1.005 | V/V |
| Output Characteristics |  |  |  |  |  |  |
| $\mathrm{V}_{\mathrm{OL}}$ | Output Swing Low | $\mathrm{I}_{\mathrm{L}}=-5 \mathrm{~mA}$ |  | 80 | 150 | mV |
| $\mathrm{V}_{\mathrm{OH}}$ | Output Swing High | $\mathrm{I}_{\mathrm{L}}=5 \mathrm{~mA}$ | 4.85 | 4.92 |  | V |
| $\mathrm{I}_{\mathrm{SC}}$ | Short Circuit Current | Short to GND ${ }^{\text {[2] }}$ | $\pm 80$ | $\pm 120$ |  | mA |
| Power Supply Performance |  |  |  |  |  |  |
| PSRR | Power Supply Rejection Ratio | $\mathrm{V}_{\mathrm{S}}$ is moved from 4.5 V to 15.5 V | 60 | 80 |  | dB |
| IS | Supply Current (Per Buffer) | No Load |  | 500 | 750 | $\mu \mathrm{A}$ |
| Dynamic Performance |  |  |  |  |  |  |
| SR | Slew Rate ${ }^{[3]}$ | $1 \mathrm{~V} \leq \mathrm{V}_{\text {OUT }} \leq 4 \mathrm{~V}, 20 \%$ to $80 \%$ | 7 | 10 |  | V/ $\mu \mathrm{s}$ |
| $\mathrm{ts}^{\text {S }}$ | Settling to +0.1\% | $\mathrm{V}_{\mathrm{O}}=2 \mathrm{~V}$ Step |  | 500 |  | ns |
| BW | -3dB Bandwidth | $\mathrm{R}_{\mathrm{L}}=10 \mathrm{k} \Omega, \mathrm{C}_{\mathrm{L}}=10 \mathrm{pF}$ |  | 12 |  | MHz |
| CS | Channel Separation | $\mathrm{f}=5 \mathrm{MHz}$ |  | 75 |  | dB |

1. Measured over the operating temperature range
2. Parameter is guaranteed (but not test) by design and characterization data
3. Slew rate is measured on rising and falling edges

## EL5421C

Quad 12MHz Rail-to-Rail Input-Output Buffer

## Electrical Characteristics

$\mathrm{V}_{\mathrm{S}^{+}}=+15 \mathrm{~V}, \mathrm{~V}_{\mathrm{S}^{-}}=0 \mathrm{~V}, \mathrm{R}_{\mathrm{L}}=10 \mathrm{k} \Omega$ and $\mathrm{C}_{\mathrm{L}}=10 \mathrm{pF}$ to $7.5 \mathrm{~V}, \mathrm{TA}=25^{\circ} \mathrm{C}$ unless otherwise specified.

| Parameter | Description | Condition | Min | Typ | Max | Unit |
| :---: | :---: | :---: | :---: | :---: | :---: | :---: |
| Input Characteristics |  |  |  |  |  |  |
| Vos | Input Offset Voltage | $\mathrm{V}_{\mathrm{CM}}=7.5 \mathrm{~V}$ |  | 2 | 14 | mV |
| $\mathrm{TCV}_{\text {OS }}$ | Average Offset Voltage Drift | [1] |  | 5 |  | $\mu \mathrm{V} /{ }^{\circ} \mathrm{C}$ |
| $\mathrm{I}_{\mathrm{B}}$ | Input Bias Current | $\mathrm{V}_{\mathrm{CM}}=7.5 \mathrm{~V}$ |  | 2 | 50 | nA |
| $\mathrm{R}_{\text {IN }}$ | Input Impedance |  |  | 1 |  | $\mathrm{G} \Omega$ |
| $\mathrm{C}_{\text {IN }}$ | Input Capacitance |  |  | 1.35 |  | pF |
| Av | Voltage Gain | $0.5 \leq \mathrm{V}_{\text {OUT }} \leq 14.5 \mathrm{~V}$ | 0.995 |  | 1.005 | V/V |
| Output Characteristics |  |  |  |  |  |  |
| $\mathrm{V}_{\mathrm{OL}}$ | Output Swing Low | $\mathrm{I}_{\mathrm{L}}=-5 \mathrm{~mA}$ |  | 80 | 150 | mV |
| $\mathrm{V}_{\mathrm{OH}}$ | Output Swing High | $\mathrm{I}_{\mathrm{L}}=5 \mathrm{~mA}$ | 14.85 | 14.92 |  | V |
| $\mathrm{I}_{\text {SC }}$ | Short Circuit Current | Short to GND ${ }^{\text {[2] }}$ | $\pm 80$ | $\pm 120$ |  | mA |
| Power Supply Performance |  |  |  |  |  |  |
| PSRR | Power Supply Rejection Ratio | $\mathrm{V}_{\mathrm{S}}$ is moved from 4.5 V to 15.5 V | 60 | 80 |  | dB |
| $\mathrm{I}_{\text {S }}$ | Supply Current (Per Buffer) | No Load |  | 500 | 750 | $\mu \mathrm{A}$ |
| Dynamic Performance |  |  |  |  |  |  |
| SR | Slew Rate ${ }^{[3]}$ | $1 \mathrm{~V} \leq \mathrm{V}_{\text {OUT }} \leq 14 \mathrm{~V}, 20 \%$ to $80 \%$ | 7 | 10 |  | V/us |
| ts | Settling to $+0.1 \%$ | $\mathrm{V}_{\mathrm{O}}=2 \mathrm{~V}$ Step |  | 500 |  | ns |
| BW | -3dB Bandwidth | $\mathrm{R}_{\mathrm{L}}=10 \mathrm{k} \Omega, \mathrm{C}_{\mathrm{L}}=10 \mathrm{pF}$ |  | 12 |  | MHz |
| CS | Channel Separation | $\mathrm{f}=5 \mathrm{MHz}$ |  | 75 |  | dB |

1. Measured over the operating temperature range
2. Parameter is guaranteed (but not test) by design and characterization data
3. Slew rate is measured on rising and falling edges

## Typical Performance Curves




Supply Current per Channel vs Temperature


Slew Rate vs Temperature


Supply Current per Channel vs Supply Voltage


Frequency Response for Various $C_{L}$



PSRR vs Frequency


Total Harmonic Distortion + Noise vs Frequency


Maximum Output Swing vs Frequency



Channel Separation vs Frequency Response



## Large Signal Transient Response



Settling Time vs Step Size


Small Signal Transient Response


## EL5421C

## Pin Description

| EL5421C | Name | Function | Equivalent Circuit |
| :---: | :---: | :---: | :---: |
| 1 | V OUTA | Buffer A Output | Circuit 1 |
| 2 | $\mathrm{V}_{\text {INA }}$ | Buffer A Input | Circuit 2 |
| 3 | $\mathrm{V}_{\text {S+ }}$ | Positive Power Supply |  |
| 4 | $\mathrm{V}_{\text {INB }}$ | Buffer B Input | (Reference Circuit 1) |
| 5 | V ${ }_{\text {OUTB }}$ | Buffer B Output | (Reference Circuit 2) |
| 6 | Voutc | Buffer C Output | (Reference Circuit 2) |
| 7 | $\mathrm{V}_{\text {INC }}$ | Buffer C Input | (Reference Circuit 1) |
| 8 | $\mathrm{V}_{\text {S- }}$ | Negative Power Supply |  |
| 9 | $\mathrm{V}_{\text {IND }}$ | Buffer D Input | (Reference Circuit 2) |
| 10 | V OUTD | Buffer D Output | (Reference Circuit 1) |

Quad 12MHz Rail-to-Rail Input-Output Buffer

## Applications Information

## Product Description

The EL5421C unity gain buffer is fabricated using a high voltage CMOS process. It exhibits Rail-to-Rail input and output capability, and has low power consumption ( $500 \mu \mathrm{~A}$ per buffer). These features make the EL5421C ideal for a wide range of general-purpose applications. When driving a load of $10 \mathrm{k} \Omega$ and 12 pF , the EL5421C has a -3dB bandwidth of 12 MHz and exhibits $10 \mathrm{~V} / \mu \mathrm{S}$ slew rate.

## Operating Voltage, Input, and Output

The EL5421C is specified with a single nominal supply voltage from 5 V to 15 V or a split supply with its total range from 5 V to 15 V . Correct operation is guaranteed for a supply range of 4.5 V to 16.5 V . Most EL5421C specifications are stable over both the full supply range and operating temperatures of $-40^{\circ} \mathrm{C}$ to $+85^{\circ} \mathrm{C}$. Parameter variations with operating voltage and/or temperature are shown in the typical performance curves.

The output swings of the EL5421C typically extend to within 80 mV of positive and negative supply rails with load currents of 5 mA . Decreasing load currents will extend the output voltage range even closer to the supply rails. Figure 1 shows the input and output waveforms for the device. Operation is from $+/-5 \mathrm{~V}$ supply with a $10 \mathrm{k} \Omega$ load connected to GND. The input is a 10 Vp -p sinusoid. The output voltage is approximately $9.985 \mathrm{~V}_{\mathrm{P}-\mathrm{P}}$.


Figure 1. Operation with Rail-to-Rail Input and Output

## Short Circuit Current Limit

The EL5421C will limit the short circuit current to +/120 mA if the output is directly shorted to the positive or the negative supply. If an output is shorted indefinitely, the power dissipation could easily increase such that the device may be damaged. Maximum reliability is maintained if the output continuous current never exceeds +/30 mA . This limit is set by the design of the internal metal interconnects.

## Output Phase Reversal

The EL5421C is immune to phase reversal as long as the input voltage is limited from $\mathrm{V}_{\mathrm{S}^{-}}-0.5 \mathrm{~V}$ to $\mathrm{V}_{\mathrm{S}^{+}}+0.5 \mathrm{~V}$. Figure 2 shows a photo of the output of the device with the input voltage driven beyond the supply rails. Although the device's output will not change phase, the input's overvoltage should be avoided. If an input voltage exceeds supply voltage by more than 0.6 V , electrostatic protection diodes placed in the input stage of the device begin to conduct and overvoltage damage could occur.


Figure 2. Operation with Beyond-the-Rails Input

## Power Dissipation

With the high-output drive capability of the EL5421C buffer, it is possible to exceed the $125^{\circ} \mathrm{C}$ 'absolute-maximum junction temperature' under certain load current conditions. Therefore, it is important to calculate the

## EL5421C <br> Quad 12MHz Rail-to-Rail Input-Output Buffer

maximum junction temperature for the application to determine if load conditions need to be modified for the buffer to remain in the safe operating area.

The maximum power dissipation allowed in a package is determined according to:

$$
P_{\text {DMAX }}=\frac{T_{\text {JMAX }}-T_{\text {AMAX }}}{\Theta_{J A}}
$$

where:
$\mathrm{T}_{\mathrm{JMAX}}=$ Maximum Junction Temperature
$\mathrm{T}_{\mathrm{AMAX}}=$ Maximum Ambient Temperature
$\theta_{\mathrm{JA}}=$ Thermal Resistance of the Package
P
Packax $=$ Maximum Power Dissipation in the

The maximum power dissipation actually produced by an IC is the total quiescent supply current times the total power supply voltage, plus the power in the IC due to the loads, or:

$$
\mathrm{P}_{\text {DMAX }}=\Sigma \mathrm{i}\left[\mathrm{~V}_{\mathrm{S}} \times \mathrm{I}_{\text {SMAX }}+\left(\mathrm{V}_{\mathrm{S}^{+-}}-\mathrm{V}_{\text {OUT }} \mathrm{i}\right) \times \mathrm{I}_{\text {LOAD }} \mathrm{i}\right]
$$

when sourcing, and:

$$
\mathrm{P}_{\text {DMAX }}=\Sigma \mathrm{i}\left[\mathrm{~V}_{\mathrm{S}} \times \mathrm{I}_{\text {SMAX }}+\left(\mathrm{V}_{\text {OUT }^{\mathrm{i}}}-\mathrm{V}_{\mathrm{S}^{-}}\right) \times \mathrm{I}_{\text {LOAD }}{ }^{\mathrm{i}]}\right.
$$

when sinking.
Where:

$$
\begin{aligned}
& \mathrm{i}=1 \text { to } 4 \text { for Quad } \\
& \mathrm{V}_{\mathrm{S}}=\text { Total Supply Voltage } \\
& \text { ISMAX } \text { = Maximum Supply Current Per Channel } \\
& \text { VOuTi = Maximum Output Voltage of the } \\
& \text { Application }
\end{aligned}
$$

$$
\mathrm{I}_{\text {LOAD }}{ }^{\mathrm{i}}=\text { Load current }
$$

If we set the two $\mathrm{P}_{\mathrm{DMAX}}$ equations equal to each other, we can solve for $\mathrm{R}_{\text {LOAD }}$ to avoid device overheat. Figure 3 and Figure 4 provide a convenient way to see if the device will overheat. The maximum safe power dissipation can be found graphically, based on the package type and the ambient temperature. By using the previous
equation, it is a simple matter to see if $\mathrm{P}_{\mathrm{DMAX}}$ exceeds the device's power derating curves. To ensure proper operation, it is important to observe the recommended derating curves shown in Figure 3 and Figure 4.


Figure 3. Package Power Dissipation vs Ambient Temperature


Figure 4. Package Power Dissipation vs Ambient Temperature

## Unused Buffers

It is recommended that any unused buffer have the input tied to the ground plane.

Quad 12MHz Rail-to-Rail Input-Output Buffer

## Driving Capacitive Loads

The EL5421C can drive a wide range of capacitive loads. As load capacitance increases, however, the -3dB bandwidth of the device will decrease and the peaking increase. The buffers drive 10 pF loads in parallel with $10 \mathrm{k} \Omega$ with just 1.5 dB of peaking, and 100 pF with 6.4 dB of peaking. If less peaking is desired in these applications, a small series resistor (usually between $5 \Omega$ and 50 $\Omega$ ) can be placed in series with the output. However, this will obviously reduce the gain slightly. Another method of reducing peaking is to add a "snubber" circuit at the output. A snubber is a shunt load consisting of a resistor in series with a capacitor. Values of $150 \Omega$ and 10 nF are typical. The advantage of a snubber is that it does not draw any DC load current or reduce the gain

## Power Supply Bypassing and Printed Circuit Board Layout

The EL5421C can provide gain at high frequency. As with any high-frequency device, good printed circuit board layout is necessary for optimum performance. Ground plane construction is highly recommended, lead lengths should be as short as possible and the power supply pins must be well bypassed to reduce the risk of oscillation. For normal single supply operation, where the $\mathrm{V}_{\mathrm{S}^{-}}$pin is connected to ground, a $0.1 \mu \mathrm{~F}$ ceramic capacitor should be placed from $\mathrm{V}_{\mathrm{S}}+$ to pin to $\mathrm{V}_{\mathrm{S}}$ - pin. A $4.7 \mu \mathrm{~F}$ tantalum capacitor should then be connected in parallel, placed in the region of the buffer. One $4.7 \mu \mathrm{~F}$ capacitor may be used for multiple devices. This same capacitor combination should be placed at each supply pin to ground if split supplies are to be used.

## General Disclaimer

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## Elantec Semiconductor, Inc.

675 Trade Zone Blvd.
Milpitas, CA 95035
Telephone: (408) 945-1323
(888) ELANTEC

Fax:
(408) 945-9305

European Office: +44-118-977-6080
Japan Technical Center: +81-45-682-5820

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